

### Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

#### Listing of Claims:

1. (Currently Amended) A three dimensional object creation system that prints objects layer by layer, the system including a ~~plurality~~series of printheads for printing the layers, the system printing at least part of each of multiple layers simultaneously,  
the system including semiconductor memory and  
wherein data defining at least one layer is stored in the semiconductor memory,  
the system is configured to enable ~~at least one first~~each printhead ~~that is initially configured to print at least part of a first~~respective layer to be dynamically reconfigured to print at least part of a ~~second~~another layer, and  
if at least one printhead ~~initially configured to print the second layer fails whilst printing said second~~its respective layer, ~~said at least one first~~each subsequent printhead is dynamically reconfigured to complete the printing of at least part of ~~said second~~the layer preceding its respective layer.
2. (Original) The system of claim 1 wherein data defining all of the layers is stored in the semiconductor memory.
3. (Original) The system of claim 1 wherein each printhead includes at least some of the semiconductor memory.
4. (Original) The system of claim 1 wherein the semiconductor memory of each printhead stores data relating to at least the part of the layer printed by the printhead.
5. (Original) The system of claim 1 wherein the semiconductor memory of each printhead stores data relating to at least part of at least another layer.
6. (Original) The system of claim 1 wherein the semiconductor memory of each printhead stores data relating to at least part of the previous layer compared to the layer currently being printed by the respective printhead.
7. (Previously Presented) The system of claim 1 including data links between

printheads.

8. (Previously Presented) The system of claim 1 including about 10 Gbytes of semiconductor memory.
9. (Cancelled)
10. (Cancelled)
11. (Original) A system as claimed in claim 1 wherein the printheads are configured to enable printing of at least two different materials in at least one layer.
12. (Previously Presented) A system as claimed in claim 11 wherein the printheads are configured such that at least one of the layers may be printed with a first set of materials and at least one other of the layers may be printed with a second set of materials, and wherein the first and second sets are not the same.
- 13-16. (Cancelled)
17. (Previously Presented) A system as claimed in claim 11 including a least two printheads, a first one of the printheads printing a first material and a second one of the printheads printing a second material, the first material being cured by a first method and the second material being cured by a second method and wherein the first and second methods are different.
18. (Original) A system as claimed in claim 1 including at least one printhead for printing material to create a printed product, and  
an object incorporation device that incorporates inorganic semiconductors into the product being printed whilst the at least one printhead prints the product.
19. (Original) A system as claimed in claim 1 including at least one object incorporation device that incorporates non-printed objects into partially completed product, the non-printed objects not being printed by the system.
20. (Original) A system as claimed in claim 1 including an object incorporation device that inserts at least one non-printed object into at least one cavity created during the printing process, the object incorporation device incorporating the at least one non-printed object into the at least one cavity during the printing of the respective printed object.

21. (Original) A system as claimed in claim 1 including at least one printhead that prints electrical connections to at least one object incorporated in the products.